Unit: mm

TOSHIBA Field Effect Transistor Silicon N Channel MOS Type (π-MOSV)

# 2SK2699

# Chopper Regulator, DC-DC Converter and Motor Drive Applications

 $\begin{array}{ll} \bullet & \text{Low drain-source ON resistance} & : \text{RDS (ON)} = 0.5 \ \Omega \ \text{(typ.)} \\ \bullet & \text{High forward transfer admittance} & : | \text{Y}_{fs}| = 11 \ \text{S (typ.)} \\ \bullet & \text{Low leakage current} & : \text{IDSS} = 100 \ \mu \text{A (max) (VDS} = 600 \ \text{V)} \\ \end{array}$ 

• Enhancement mode :  $V_{th} = 2.0 \sim 4.0 \text{ V (V}_{DS} = 10 \text{ V, I}_{D} = 1 \text{ mA})$ 

#### Absolute Maximum Ratings (Ta = 25°C)

| Characteris             | stics                  | Symbol           | Rating  | Unit |  |
|-------------------------|------------------------|------------------|---------|------|--|
| Drain-source voltage    |                        | $V_{DSS}$        | 600     | V    |  |
| Drain-gate voltage (R   | <sub>SS</sub> = 20 kΩ) | $V_{DGR}$        | 600     | ٧    |  |
| Gate-source voltage     |                        | V <sub>GSS</sub> | ±30     | V    |  |
| Drain current           | DC (Note 1)            | I <sub>D</sub>   | 12      | Α    |  |
|                         | Pulse (Note 1)         | $I_{DP}$         | 48      | Α    |  |
| Drain power dissipation | n (Tc = 25°C)          | $P_{D}$          | 150     | W    |  |
| Single pulse avalanche  | e energy<br>(Note 2)   | E <sub>AS</sub>  | 605     | mJ   |  |
| Avalanche current       |                        | I <sub>AR</sub>  | 12      | Α    |  |
| Repetitive avalanche e  | nergy (Note 3)         | E <sub>AR</sub>  | 15      | mJ   |  |
| Channel temperature     |                        | T <sub>ch</sub>  | 150     | °C   |  |
| Storage temperature ra  | ange                   | T <sub>stg</sub> | -55~150 | °C   |  |

Weight: 4.6 g (typ.)

Note: Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings. Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/Derating Concept and Methods) and individual reliability data (i.e. reliability test report and estimated failure rate, etc).

#### **Thermal Characteristics**

| Characteristics                        | Symbol                 | Max   | Unit |
|--|------------------------|-------|------|
| Thermal resistance, channel to case    | R <sub>th (ch-c)</sub> | 0.833 | °C/W |
| Thermal resistance, channel to ambient | R <sub>th (ch-a)</sub> | 50    | °C/W |

Note 1: Ensure that the channel temperature does not exceed 150°C.

Note 2:  $V_{DD}$  = 90 V,  $T_{ch}$  = 25°C (initial), L = 7.35 mH,  $R_{G}$  = 25  $\Omega$ ,  $I_{AR}$  = 12 A

Note 3: Repetitive rating: pulse width limited by maximum channel temperature

This transistor is an electrostatic-sensitive device.

Please handle with caution.



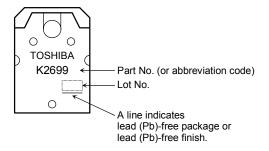
## Electrical Characteristics (Ta = 25°C)

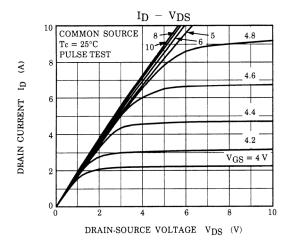
| Charac  | eteristics      | Symbol                | Test Condition  | Min | Тур. | Max  | Unit |
|---|-----------------|-----------------------|---|-----|------|------|------|
| Gate leakage cu                                 | ırrent          | I <sub>GSS</sub>      | V <sub>GS</sub> = ±25 V, V <sub>DS</sub> = 0 V                            | _   | _    | ±10  | μΑ   |
| Gate-source bre                                 | eakdown voltage | V (BR) GSS            | I <sub>G</sub> = ±10 μA, V <sub>DS</sub> = 0 V                            | ±30 | _    | _    | V    |
| Drain cut-off cui                               | rrent           | I <sub>DSS</sub>      | V <sub>DS</sub> = 600 V, V <sub>GS</sub> = 0 V                            | _   | _    | 100  | μA   |
| Drain-source br                                 | eakdown voltage | V <sub>(BR) DSS</sub> | I <sub>D</sub> = 10 mA, V <sub>GS</sub> = 0 V                             | 600 | _    | _    | V    |
| Gate threshold v                                | oltage/         | $V_{th}$              | V <sub>DS</sub> = 10 V, I <sub>D</sub> = 1 mA                             | 2.0 | _    | 4.0  | V    |
| Drain-source Ol                                 | N resistance    | R <sub>DS (ON)</sub>  | V <sub>GS</sub> = 10 V, I <sub>D</sub> = 6 A                              | _   | 0.5  | 0.65 | Ω    |
| Forward transfer                                | r admittance    | Y <sub>fs</sub>       | V <sub>DS</sub> = 10 V, I <sub>D</sub> = 6 A                              | 6.0 | 11.0 | _    | S    |
| Input capacitano                                | e               | C <sub>iss</sub>      |   | _   | 2600 | _    |      |
| Reverse transfer capacitance                    |                 | C <sub>rss</sub>      | V <sub>DS</sub> = 10 V, V <sub>GS</sub> = 0 V, f = 1 MHz                  | _   | 270  | _    | pF   |
| Output capacitance                              |                 | C <sub>oss</sub>      |   | _   | 820  | _    |      |
| Switching time                                  | Rise time       | t <sub>r</sub>        | $V_{GS}$ $V_{OV}$ $V_{OU}$ $V_{OU}$ $V_{OU}$ $V_{OU}$ $V_{OU}$ $V_{OU}$   | _   | 45   | _    | - ns |
|   | Turn-on time    | t <sub>on</sub>       |   | _   | 75   | _    |      |
|   | Fall time       | t <sub>f</sub>        |   | _   | 65   | _    | 115  |
|   | Turn-off time   | t <sub>off</sub>      | Duty $\leq 1\%$ , $t_{\rm W} = 10 \mu \rm s$                              |     | 270  |      |      |
| Total gate charge (gate-source plus gate-drain) |                 | Qg                    |   |     | 58   |      |      |
| Gate-source charge                              |                 | $Q_{gs}$              | $V_{DD} \approx 480 \text{ V}, V_{GS} = 10 \text{ V}, I_D = 12 \text{ A}$ |     | 37   |      | nC   |
| Gate-drain ("miller") Charge                    |                 | $Q_{gd}$              |   |     | 21   |      |      |

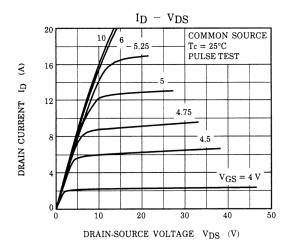
## Source-Drain Diode Ratings and Characteristics (Ta = 25°C)

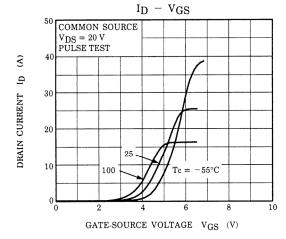
| Characteristics                           | Symbol           | Test Condition                                | Min | Тур. | Max  | Unit |
|---|------------------|---|-----|------|------|------|
| Continuous drain reverse current (Note 1) | I <sub>DR</sub>  |   | _   | _    | 12   | Α    |
| Pulse drain reverse current (Note 1)      | I <sub>DRP</sub> | _   | _   | _    | 48   | Α    |
| Forward voltage (diode)                   | V <sub>DSF</sub> | I <sub>DR</sub> = 12 A, V <sub>GS</sub> = 0 V | _   | _    | -1.7 | V    |
| Reverse recovery time                     | t <sub>rr</sub>  | I <sub>DR</sub> = 12 A, V <sub>GS</sub> = 0 V | 1   | 460  |      | ns   |
| Reverse recovery charge                   | $Q_{rr}$         | dI <sub>DR</sub> / dt = 100 A / μs            |     | 4.8  |      | μC   |

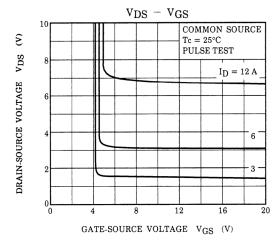
## Marking

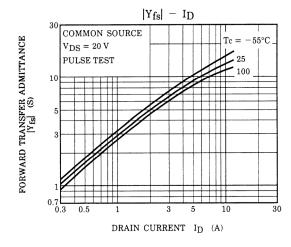


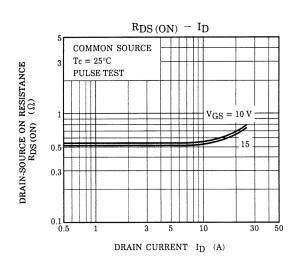


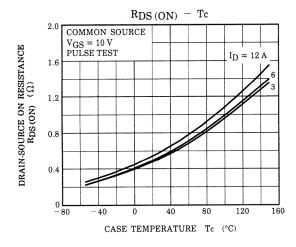


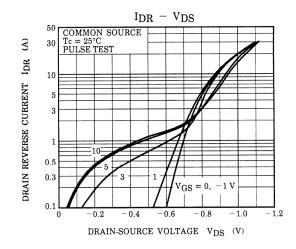


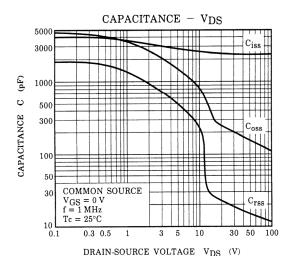


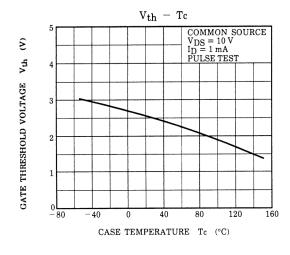


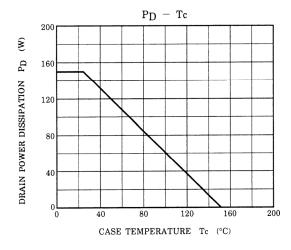


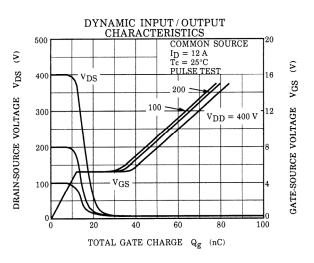




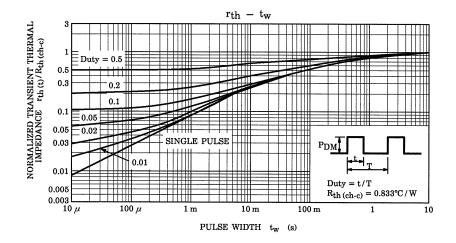


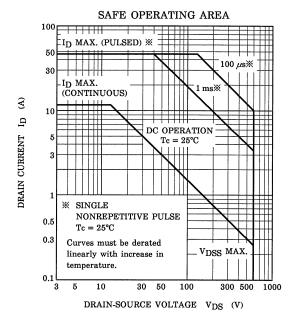


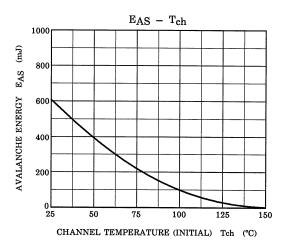


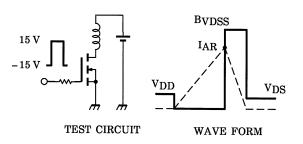


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$$\begin{aligned} &R_G = 25~\Omega \\ &V_{DD} = 90~V,~L = 7.35~mH \end{aligned} \qquad E_{AS} = \frac{1}{2} \cdot L \cdot I^2 \cdot \left( \frac{B_{VDSS}}{B_{VDSS} - V_{DD}} \right)$$

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